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Intel[®] Arria[®] 10 Device Overview



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Intel[®] Arria[®] 10 Device Overview

The Intel[®] Arria[®] 10 device family consists of high-performance and power-efficient 20 nm mid-range FPGAs and SoCs.

Intel Arria 10 device family delivers:

- Higher performance than the previous generation of mid-range and high-end FPGAs.
- Power efficiency attained through a comprehensive set of power-saving technologies.

The Intel Arria 10 devices are ideal for high performance, power-sensitive, midrange applications in diverse markets.

Market	Applications
Wireless	Channel and switch cards in remote radio headsMobile backhaul
Wireline	 40G/100G muxponders and transponders 100G line cards Bridging Aggregation
Broadcast	 Studio switches Servers and transport Videoconferencing Professional audio and video
Computing and Storage	Flash cacheCloud computing serversServer acceleration
Medical	Diagnostic scannersDiagnostic imaging
Military	 Missile guidance and control Radar Electronic warfare Secure communications

Table 1. Sample Markets and Ideal Applications for Intel Arria 10 Devices

Related Information

Intel Arria 10 Device Handbook: Known Issues Lists the planned updates to the *Intel Arria 10 Device Handbook* chapters.

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Key Advantages of Intel Arria 10 Devices

Table 2. Key Advantages of the Intel Arria 10 Device Family

Advantage	Supporting Feature
Enhanced core architecture	 Built on TSMC's 20 nm process technology 60% higher performance than the previous generation of mid-range FPGAs 15% higher performance than the fastest previous-generation FPGA
High-bandwidth integrated transceivers	 Short-reach rates up to 25.8 Gigabits per second (Gbps) Backplane capability up to 12.5 Gbps Integrated 10GBASE-KR and 40GBASE-KR4 Forward Error Correction (FEC)
Improved logic integration and hard IP blocks	 8-input adaptive logic module (ALM) Up to 65.6 megabits (Mb) of embedded memory Variable-precision digital signal processing (DSP) blocks Fractional synthesis phase-locked loops (PLLs) Hard PCI Express Gen3 IP blocks Hard memory controllers and PHY up to 2,400 Megabits per second (Mbps)
Second generation hard processor system (HPS) with integrated ARM* Cortex*-A9* MPCore* processor	 Tight integration of a dual-core ARM Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Intel Arria 10 system-on-a-chip (SoC) Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric
Advanced power savings	 Comprehensive set of advanced power saving features Power-optimized MultiTrack routing and core architecture Up to 40% lower power compared to previous generation of mid-range FPGAs Up to 60% lower power compared to previous generation of high-end FPGAs

Summary of Intel Arria 10 Features

Table 3. Summary of Features for Intel Arria 10 Devices

Feature	Description
Technology	 TSMC's 20-nm SoC process technology Allows operation at a lower V_{CC} level of 0.82 V instead of the 0.9 V standard V_{CC} core voltage
Packaging	 1.0 mm ball-pitch Fineline BGA packaging 0.8 mm ball-pitch Ultra Fineline BGA packaging Multiple devices with identical package footprints for seamless migration between different FPGA densities Devices with compatible package footprints allow migration to next generation high-end Stratix[®] 10 devices RoHS, leaded⁽¹⁾, and lead-free (Pb-free) options
High-performance FPGA fabric	 Enhanced 8-input ALM with four registers Improved multi-track routing architecture to reduce congestion and improve compilation time Hierarchical core clocking architecture Fine-grained partial reconfiguration
Internal memory blocks	 M20K—20-Kb memory blocks with hard error correction code (ECC) Memory logic array block (MLAB)—640-bit memory
	continued

⁽¹⁾ Contact Intel for availability.



Feature		Description
Embedded Hard IP blocks	Variable-precision DSP	 Native support for signal processing precision levels from 18 x 19 to 54 x 54 Native support for 27 x 27 multiplier mode 64-bit accumulator and cascade for systolic finite impulse responses (FIRs) Internal coefficient memory banks Preadder/subtractor for improved efficiency Additional pipeline register to increase performance and reduce power Supports floating point arithmetic: Perform multiplication, addition, subtraction, multiply-add, multiply-subtract, and complex multiplication. Supports multiplication with accumulation capability, cascade summation, and cascade subtraction capability. Dynamic accumulator reset control. Support direct vector dot and complex multiplication chaining multiply floating point DSP blocks.
	Memory controller	DDR4, DDR3, and DDR3L
	PCI Express*	PCI Express (PCIe*) Gen3 (x1, x2, x4, or x8), Gen2 (x1, x2, x4, or x8) and Gen1 (x1, x2, x4, or x8) hard IP with complete protocol stack, endpoint, and root port
	Transceiver I/O	 10GBASE-KR/40GBASE-KR4 Forward Error Correction (FEC) PCS hard IPs that support: 10-Gbps Ethernet (10GbE) PCIe PIPE interface Interlaken Gbps Ethernet (GbE) Common Public Radio Interface (CPRI) with deterministic latency support Gigabit-capable passive optical network (GPON) with fast lock-time support 13.5G JESD204b 8B/10B, 64B/66B, 64B/67B encoders and decoders Custom mode support for proprietary protocols
Core clock networks	 667 MHz externa 800 MHz LVDS in Global, regional, and 	c clocking, depending on the application: I memory interface clocking with 2,400 Mbps DDR4 interface terface clocking with 1,600 Mbps LVDS interface I peripheral clock networks are not used can be gated to reduce dynamic power
Phase-locked loops (PLLs)	 Support integer r Fractional mode s Integer PLLs: Adjacent to gene 	nthesis, clock delay compensation, and zero delay buffering (ZDB) node and fractional mode support with third-order delta-sigma modulation
FPGA General-purpose I/Os (GPIOs)	On-chip termination	ry pair can be configured as receiver or transmitter (OCT) -ended LVTTL/LVCMOS interfacing
External Memory Interface	 DDR4—speeds up DDR3—speeds up 	Iller— DDR4, DDR3, and DDR3L support to 1,200 MHz/2,400 Mbps to 1,067 MHz/2,133 Mbps Ier—provides support for RLDRAM 3 ⁽²⁾ , QDR IV ⁽²⁾ , and QDR II+ continued



Feature	Description							
Low-power serial transceivers	 Continuous operating range: Intel Arria 10 GX-1 Gbps to 17.4 Gbps Intel Arria 10 GT-1 Gbps to 25.8 Gbps Backplane support: Intel Arria 10 GX-up to 12.5 Intel Arria 10 GT-up to 12.5 Extended range down to 125 Mbps with oversampling ATX transmit PLLs with user-configurable fractional synthesis capability Electronic Dispersion Compensation (EDC) support for XFP, SFP+, QSFP, and CFP optical module Adaptive linear and decision feedback equalization Transmitter pre-emphasis and de-emphasis Dynamic partial reconfiguration of individual transceiver channels							
HPS (Intel Arria 10 SX devices only)	Processor and system • Dual-core ARM Cortex-A9 MPCore 1.5 GHz overdrive capability • 256 KB on-chip RAM and 64 KB on • System peripherals—general-purpor memory access (DMA) controller, F clock and reset managers • Security features—anti-tamper, see Standard (AES) and authentication • ARM CoreSight* JTAG debug acces trace storage	-chip ROM ose timers, watchdog timers, direct PGA configuration manager, and cure boot, Advanced Encryption I (SHA)						
	 External interfaces Hard memory interface—Hard mem and 2,133 Mbps DDR3), Quad seria controller, NAND flash controller, di controller, Secure Digital/MultiMedi Communication interface— 10/100 control (MAC), USB On-The-GO (O' UART 16550, serial peripheral inter HPS GPIO interfaces (48 direct-share) 	al peripheral interface (QSPI) flash irect memory access (DMA) iaCard (SD/MMC) controller I/1000 Ethernet media access TG) controllers, I ² C controllers, rface (SPI), and up to 62						
	Interconnects to core High-performance ARM AMBA* AXI simultaneous read and write HPS-FPGA bridges—include the FP lightweight HPS-to-FPGA bridges th transactions to slaves in the HPS, a Configuration bridge that allows HF configure the core logic via dedicat FPGA-to-HPS SDRAM controller bri interfaces for the multiport front en controller	GA-to-HPS, HPS-to-FPGA, and hat allow the FPGA fabric to issue and vice versa PS configuration manager to ted 32-bit configuration port dge—provides configuration						
Configuration	 Tamper protection—comprehensive design protection to pro Enhanced 256-bit advanced encryption standard (AES) design Configuration via protocol (CvP) using PCIe Gen1, Gen2, or 	gn security with authentication						
		continued						

 $^{^{(2)}\,}$ Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.



Feature	Description
	 Dynamic reconfiguration of the transceivers and PLLs Fine-grained partial reconfiguration of the core fabric Active Serial x4 Interface
Power management	 SmartVID Low static power device options Programmable Power Technology Intel Quartus Prime integrated power analysis
Software and tools	 Intel Quartus Prime design suite Transceiver toolkit Platform Designer system integration tool DSP Builder for Intel FPGAs OpenCL[™] support Intel SoC FPGA Embedded Design Suite (EDS)

Related Information

Intel Arria 10 Transceiver PHY Overview Provides details on Intel Arria 10 transceivers.

Intel Arria 10 Device Variants and Packages

Table 4. Device Variants for the Intel Arria 10 Device Family

Variant	Description
Intel Arria 10 GX	FPGA featuring 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability.
Intel Arria 10 GT	 FPGA featuring: 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability. 25.8 Gbps transceivers for supporting CAUI-4 and CEI-25G applications with CFP2 and CFP4 modules.
Intel Arria 10 SX	SoC integrating ARM-based HPS and FPGA featuring 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability.

Intel Arria 10 GX

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 GX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

Related Information

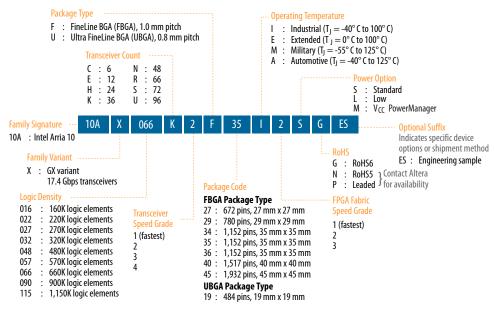
Intel FPGA Product Selector

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Available Options

Figure 1. Sample Ordering Code and Available Options for Intel Arria 10 GX Devices



Related Information

Transceiver Performance for Intel Arria 10 GX/SX Devices Provides more information about the transceiver speed grade.



Maximum Resources

Table 5.Maximum Resource Counts for Intel Arria 10 GX Devices (GX 160, GX 220, GX
270, GX 320, and GX 480)

Resource		Product Line						
		GX 160	GX 220	GX 270	GX 320	GX 480		
Logic Elements	(LE) (K)	160	220	270	320	480		
ALM		61,510	80,330	101,620	119,900	183,590		
Register		246,040	321,320	406,480	479,600	734,360		
Memory (Kb)	M20K	8,800	11,740	15,000	17,820	28,620		
	MLAB	1,050	1,690	2,452	2,727	4,164		
Variable-precisi	on DSP Block	156	192	830	985	5 1,368		
18 x 19 Multipli	er	312	384	1,660	1,970 2,736			
PLL	Fractional Synthesis	6	6	8	8	12		
	I/O	6	6	8	8	12		
17.4 Gbps Trans	sceiver	12	12	24	24	36		
GPIO ⁽³⁾		288 288 384 3		384	492			
LVDS Pair ⁽⁴⁾		120	120	168	168	222		
PCIe Hard IP BI	ock	1	1	2	2	2		
Hard Memory C	ontroller	6	6	8	8	12		

⁽³⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁴⁾ Each LVDS I/O pair can be used as differential input or output.



Table 6.Maximum Resource Counts for Intel Arria 10 GX Devices (GX 570, GX 660, GX 900, and GX 1150)

Re	source		Produc	t Line		
		GX 570	GX 660	GX 900	GX 1150	
Logic Elements (LE) (K)		570	660	900	1,150	
ALM		217,080	251,680	339,620	427,200	
Register		868,320	1,006,720	1,358,480	1,708,800	
Memory (Kb)	M20K	36,000	42,620	48,460	54,260	
	MLAB	5,096	5,788	9,386	12,984	
Variable-precis	sion DSP Block	1,523	1,687	1,518	1,518	
18 x 19 Multip	lier	3,046	3,374	3,036	3,036	
PLL	Fractional Synthesis	16	16	32	32	
	I/O	16	16	16	16	
17.4 Gbps Trai	nsceiver	48	48 48 96		96	
GPIO ⁽³⁾		696	696	768	768	
LVDS Pair ⁽⁴⁾		324	324	384	384	
PCIe Hard IP E	Block	2	2	4	4	
Hard Memory	Controller	16	16	16	16	

Package Plan

Table 7.Package Plan for Intel Arria 10 GX Devices (U19, F27, and F29)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	U19 (19 mm × 19 mm, 484-pin UBGA)			(19 mm × 19 mm, (27 mm × 27 mm,					F29 mm × 29 n 30-pin FBG/	
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	
GX 160	48	192	6	48	192	12	48	240	12	
GX 220	48	192	6	48	192	12	48	240	12	
GX 270	-	-	_	48	192	12	48	312	12	
GX 320	-	-	_	48	192	12	48	312	12	
GX 480	-	_	_	_	_	_	48	312	12	



Table 8. Package Plan for Intel Arria 10 GX Devices (F34, F35, NF40, and KF40)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	F34 (35 mm × 35 mm, 1152-pin FBGA)			F35 (35 mm × 35 mm, 1152-pin FBGA)			KF40 (40 mm × 40 mm, 1517-pin FBGA)			NF40 (40 mm × 40 mm, 1517-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
GX 270	48	336	24	48	336	24	_	-	_	_	-	-
GX 320	48	336	24	48	336	24	_	-	-	_	-	-
GX 480	48	444	24	48	348	36	_	-	-	_	-	-
GX 570	48	444	24	48	348	36	96	600	36	48	540	48
GX 660	48	444	24	48	348	36	96	600	36	48	540	48
GX 900	-	504	24	_	-	-	_	-	-	_	600	48
GX 1150	-	504	24	-	-	-	_	_	-	_	600	48

Table 9. Package Plan for Intel Arria 10 GX Devices (RF40, NF45, SF45, and UF45)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	RF40 (40 mm × 40 mm, 1517-pin FBGA)		NF45 (45 mm × 45 mm) 1932-pin FBGA)			SF45 (45 mm × 45 mm) 1932-pin FBGA)			UF45 (45 mm × 45 mm) 1932-pin FBGA)			
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
GX 900	_	342	66	_	768	48	_	624	72	_	480	96
GX 1150	_	342	66	_	768	48	_	624	72	_	480	96

Related Information

I/O and High-Speed Differential I/O Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.

Intel Arria 10 GT

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 GT devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

Related Information

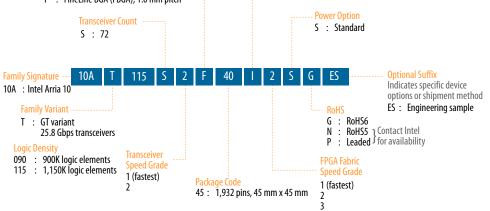
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Available Options







Maximum Resources

Table 10. Maximum Resource Counts for Intel Arria 10 GT Devices

Reso	urce	Produ	ct Line	
		GT 900	GT 1150	
Logic Elements (LE) (K)		900	1,150	
ALM		339,620	427,200	
Register		1,358,480	1,708,800	
Memory (Kb)	M20K	48,460	54,260	
	MLAB	9,386	12,984	
Variable-precision DSP Block		1,518	1,518	
18 x 19 Multiplier		3,036	3,036	
PLL	Fractional Synthesis	32	32	
	I/O	16	16	
Transceiver	17.4 Gbps	72 ⁽⁵⁾	72 ⁽⁵⁾	
	25.8 Gbps	6	6	
GPIO ⁽⁶⁾		624	624	
LVDS Pair ⁽⁷⁾		312	312	
PCIe Hard IP Block		4	4	
Hard Memory Controller		16	16	

Related Information

Intel Arria 10 GT Channel Usage

Configuring GT/GX channels in Intel Arria 10 GT devices.

Package Plan

Table 11.Package Plan for Intel Arria 10 GT Devices

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	SF45 (45 mm × 45 mm, 1932-pin FBGA)						
	3 V I/O	LVDS I/O	XCVR				
GT 900	-	624	72				
GT 1150	-	624	72				

⁽⁵⁾ If all 6 GT channels are in use, 12 of the GX channels are not usable.

⁽⁶⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁷⁾ Each LVDS I/O pair can be used as differential input or output.



Related Information

 $\rm I/O$ and High-Speed Differential I/O Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.

Intel Arria 10 SX

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

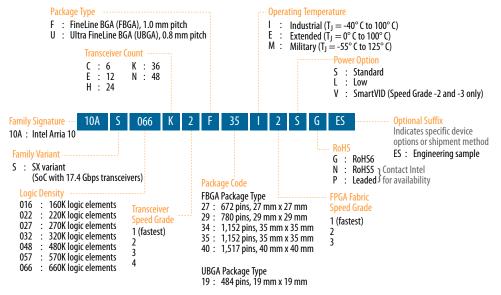
Related Information

Intel FPGA Product Selector

Provides the latest information on Intel products.

Available Options

Figure 3. Sample Ordering Code and Available Options for Intel Arria 10 SX Devices



Related Information

Transceiver Performance for Intel Arria 10 GX/SX Devices Provides more information about the transceiver speed grade.



Maximum Resources

Table 12. Maximum Resource Counts for Intel Arria 10 SX Devices

Reso	ource			I	Product Line			
		SX 160	SX 220	SX 270	SX 320	SX 480	SX 570	SX 660
Logic Elements	s (LE) (K)	160	220	270	320	480	570	660
ALM		61,510	80,330	101,620	119,900	183,590	217,080	251,680
Register		246,040	321,320	406,480	479,600	734,360	868,320	1,006,720
Memory (Kb)	M20K	8,800	11,740	15,000	17,820	28,620	36,000	42,620
	MLAB	1,050	1,690	2,452	2,727	4,164	5,096	5,788
Variable-precision DSP Block		156	192	830	985	1,368	1,523	1,687
18 x 19 Multip	lier	312	384	1,660	1,970	2,736	3,046	3,374
PLL	Fractional Synthesis	6	6	8	8	12	16	16
	I/O	6	6	8	8	12	16	16
17.4 Gbps Tra	nsceiver	12	12	24	24	36	48	48
GPIO ⁽⁸⁾		288	288	384	384	492	696	696
LVDS Pair ⁽⁹⁾		120	120	168	168	174	324	324
PCIe Hard IP E	Block	1	1	2	2	2	2	2
Hard Memory Controller		6	6	8	8	12	16	16
ARM Cortex-As Processor	9 MPCore	Yes	Yes	Yes	Yes	Yes	Yes	Yes

Package Plan

Table 13.Package Plan for Intel Arria 10 SX Devices (U19, F27, F29, and F34)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	U19 (19 mm × 19 mm, 484-pin UBGA)		F27 (27 mm × 27 mm, 672-pin FBGA)		F29 (29 mm × 29 mm, 780-pin FBGA)			F34 (35 mm × 35 mm, 1152-pin FBGA)				
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
SX 160	48	144	6	48	192	12	48	240	12	_	-	-
SX 220	48	144	6	48	192	12	48	240	12	_	-	-
SX 270	-	-	_	48	192	12	48	312	12	48	336	24
SX 320	-	-	_	48	192	12	48	312	12	48	336	24
		•									conti	nued

⁽⁸⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁹⁾ Each LVDS I/O pair can be used as differential input or output.



Product Line	U19 (19 mm × 19 mm, 484-pin UBGA)		F27 (27 mm × 27 mm, 672-pin FBGA)		F29 (29 mm × 29 mm, 780-pin FBGA)			F34 (35 mm × 35 mm, 1152-pin FBGA)				
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
SX 480	-	-	_	_	-	-	48	312	12	48	444	24
SX 570	-	-	_	_	-	-	_	_	-	48	444	24
SX 660	-	-	-	-	-	-	_	-	-	48	444	24

Table 14. Package Plan for Intel Arria 10 SX Devices (F35, KF40, and NF40)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	F35 (35 mm × 35 mm, 1152-pin FBGA)				KF40 mm × 40 n 17-pin FBG		NF40 (40 mm × 40 mm, 1517-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR	3 V I/O LVDS I/O XCVR		3 V I/O	LVDS I/O	XCVR	
SX 270	48	336	24	-	_	_	-	-	_
SX 320	48	336	24	-	_	_	_	_	_
SX 480	48	348	36	-	_	_	-	-	_
SX 570	48	348	36	96	600	36	48	540	48
SX 660	48	348	36	96	600	36	48	540	48

Related Information

I/O and High-Speed Differential I/O Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.



I/O Vertical Migration for Intel Arria 10 Devices

Figure 4. Migration Capability Across Intel Arria 10 Product Lines

- The arrows indicate the migration paths. The devices included in each vertical migration path are shaded. Devices with fewer resources in the same path have lighter shades.
- To achieve the full I/O migration across product lines in the same migration path, restrict I/Os and transceivers usage to match the product line with the lowest I/O and transceiver counts.
- An LVDS I/O bank in the source device may be mapped to a 3 V I/O bank in the target device. To use
 memory interface clock frequency higher than 533 MHz, assign external memory interface pins only to
 banks that are LVDS I/O in both devices.
- There may be nominal 0.15 mm package height difference between some product lines in the same package type.
 - Package Product Variant Line U19 F27 KF40 NF40 RF40 NF45 SF45 UF45 F29 F34 F35 GX 160 GX 220 GX 270 GX 320 Intel® Arria® 10 GX GX 480 GX 570 GX 660 GX 900 GX 1150 GT 900 Intel Arria 10 GT GT 1150 SX 160 SX 220 SX 270 Intel Arria 10 SX SX 320 SX 480 SX 570 SX 660
- Some migration paths are not shown in the Intel Quartus Prime software Pin Migration View.

Note: To verify the pin migration compatibility, use the **Pin Migration View** window in the Intel Quartus Prime software Pin Planner.

Adaptive Logic Module

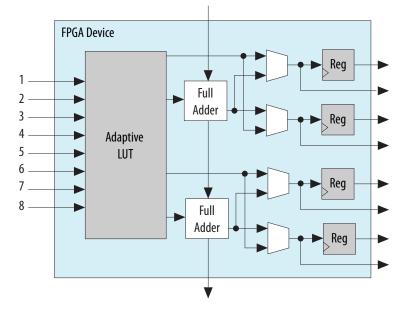
Intel Arria 10 devices use a 20 nm ALM as the basic building block of the logic fabric.

The ALM architecture is the same as the previous generation FPGAs, allowing for efficient implementation of logic functions and easy conversion of IP between the device generations.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than the traditional two-register per LUT architecture.



Figure 5. ALM for Intel Arria 10 Devices



The Intel Quartus Prime software optimizes your design according to the ALM logic structure and automatically maps legacy designs into the Intel Arria 10 ALM architecture.

Variable-Precision DSP Block

The Intel Arria 10 variable precision DSP blocks support fixed-point arithmetic and floating-point arithmetic.

Features for fixed-point arithmetic:

- High-performance, power-optimized, and fully registered multiplication operations
- 18-bit and 27-bit word lengths
- Two 18 x 19 multipliers or one 27 x 27 multiplier per DSP block
- Built-in addition, subtraction, and 64-bit double accumulation register to combine multiplication results
- Cascading 19-bit or 27-bit when pre-adder is disabled and cascading 18-bit when pre-adder is used to form the tap-delay line for filtering applications
- Cascading 64-bit output bus to propagate output results from one block to the next block without external logic support
- Hard pre-adder supported in 19-bit and 27-bit modes for symmetric filters
- Internal coefficient register bank in both 18-bit and 27-bit modes for filter implementation
- 18-bit and 27-bit systolic finite impulse response (FIR) filters with distributed output adder
- Biased rounding support



Features for floating-point arithmetic:

- A completely hardened architecture that supports multiplication, addition, subtraction, multiply-add, and multiply-subtract
- Multiplication with accumulation capability and a dynamic accumulator reset control
- Multiplication with cascade summation capability
- Multiplication with cascade subtraction capability
- Complex multiplication
- Direct vector dot product
- Systolic FIR filter

Table 15. Variable-Precision DSP Block Configurations for Intel Arria 10 Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resources
Medium precision fixed point	Two 18 x 19	1
High precision fixed or Single precision floating point	One 27 x 27	1
Fixed point FFTs	One 19 x 36 with external adder	1
Very high precision fixed point	One 36 x 36 with external adder	2
Double precision floating point	One 54 x 54 with external adder	4

Table 16. Resources for Fixed-Point Arithmetic in Intel Arria 10 Devices

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant	Product Line	Variable- precision DSP Block		put and Output ons Operator	18 x 19 Multiplier Adder Sum	18 x 18 Multiplier Adder
		DSP BIOCK	18 x 19 Multiplier	27 x 27 Multiplier	Mode Mode	Summed with 36 bit Input
AIntel Arria 10 GX	GX 160	156	312	156	156	156
GX	GX 220	192	384	192	192	192
	GX 270	830	1,660	830	830	830
	GX 320	984	1,968	984	984	984
	GX 480	1,368	2,736	1,368	1,368	1,368
	GX 570	1,523	3,046	1,523	1,523	1,523
	GX 660	1,687	3,374	1,687	1,687	1,687
	GX 900	1,518	3,036	1,518	1,518	1,518
	GX 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10 GT	GT 900	1,518	3,036	1,518	1,518	1,518
GI	GT 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10 SX	SX 160	156	312	156	156	156
	SX 220	192	384	192	192	192
	SX 270	830	1,660	830	830	830
						continued



Variant	Product Line	Variable- precision	Independent In Multiplicatio		18 x 19 Multiplier	18 x 18 Multiplier
		DSP Block	18 x 19 Multiplier	27 x 27 Multiplier	Adder Sum Mode	Adder Summed with 36 bit Input
	SX 320	984	1,968	984	984	984
	SX 480	1,368	2,736	1,368	1,368	1,368
	SX 570	1,523	3,046	1,523	1,523	1,523
	SX 660	1,687	3,374	1,687	1,687	1,687

Table 17. Resources for Floating-Point Arithmetic in Intel Arria 10 Devices

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant	Product Line	Variable- precision DSP Block	Single Precision Floating-Point Multiplication Mode	Single-Precision Floating-Point Adder Mode	Single- Precision Floating-Point Multiply Accumulate Mode	Peak Giga Floating- Point Operations per Second (GFLOPs)
Intel Arria 10 GX	GX 160	156	156	156	156	140
GA	GX 220	192	192	192	192	173
	GX 270	830	830	830	830	747
	GX 320	984	984	984	984	886
	GX 480	1,369	1,368	1,368	1,368	1,231
	GX 570	1,523	1,523	1,523	1,523	1,371
	GX 660	1,687	1,687	1,687	1,687	1,518
	GX 900	1,518	1,518	1,518	1,518	1,366
	GX 1150	1,518	1,518	1,518	1,518	1,366
Intel Arria 10	GT 900	1,518	1,518	1,518	1,518	1,366
GT	GT 1150	1,518	1,518	1,518	1,518	1,366
Intel Arria 10	SX 160	156	156	156	156	140
SX	SX 220	192	192	192	192	173
	SX 270	830	830	830	830	747
	SX 320	984	984	984	984	886
	SX 480	1,369	1,368	1,368	1,368	1,231
	SX 570	1,523	1,523	1,523	1,523	1,371
	SX 660	1,687	1,687	1,687	1,687	1,518

Embedded Memory Blocks

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.



Types of Embedded Memory

The Intel Arria 10 devices contain two types of memory blocks:

- 20 Kb M20K blocks—blocks of dedicated memory resources. The M20K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide and shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Intel Arria 10 devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB.

Embedded Memory Capacity in Intel Arria 10 Devices

	Product	M2	:0K	ML	AB	Total RAM Bit
Variant	Line	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	(Kb)
Intel Arria 10 GX	GX 160	440	8,800	1,680	1,050	9,850
	GX 220	587	11,740	2,703	1,690	13,430
	GX 270	750	15,000	3,922	2,452	17,452
	GX 320	891	17,820	4,363	2,727	20,547
	GX 480	1,431	28,620	6,662	4,164	32,784
	GX 570	1,800	36,000	8,153	5,096	41,096
	GX 660	2,131	42,620	9,260	5,788	48,408
	GX 900	2,423	48,460	15,017	9,386	57,846
	GX 1150	2,713	54,260	20,774	12,984	67,244
Intel Arria 10 GT	GT 900	2,423	48,460	15,017	9,386	57,846
	GT 1150	2,713	54,260	20,774	12,984	67,244
Intel Arria 10 SX	SX 160	440	8,800	1,680	1,050	9,850
	SX 220	587	11,740	2,703	1,690	13,430
	SX 270	750	15,000	3,922	2,452	17,452
	SX 320	891	17,820	4,363	2,727	20,547
	SX 480	1,431	28,620	6,662	4,164	32,784
	SX 570	1,800	36,000	8,153	5,096	41,096
	SX 660	2,131	42,620	9,260	5,788	48,408

Table 18. Embedded Memory Capacity and Distribution in Intel Arria 10 Devices



Embedded Memory Configurations for Single-port Mode

Table 19. Single-port Embedded Memory Configurations for Intel Arria 10 Devices

This table lists the maximum configurations supported for single-port RAM and ROM modes.

Memory Block	Depth (bits)	Programmable Width
MLAB	32	x16, x18, or x20
	64 (10)	x8, x9, x10
М20К	512	x40, x32
	1К	x20, x16
	2К	x10, x8
	4К	x5, x4
	8К	x2
	16K	×1

Clock Networks and PLL Clock Sources

The clock network architecture is based on Intel's global, regional, and peripheral clock structure. This clock structure is supported by dedicated clock input pins, fractional clock synthesis PLLs, and integer I/O PLLs.

Clock Networks

The Intel Arria 10 core clock networks are capable of up to 800 MHz fabric operation across the full industrial temperature range. For the external memory interface, the clock network supports the hard memory controller with speeds up to 2,400 Mbps in a quarter-rate transfer.

To reduce power consumption, the Intel Quartus Prime software identifies all unused sections of the clock network and powers them down.

Fractional Synthesis and I/O PLLs

Intel Arria 10 devices contain up to 32 fractional synthesis PLLs and up to 16 I/O PLLs that are available for both specific and general purpose uses in the core:

- Fractional synthesis PLLs—located in the column adjacent to the transceiver blocks
- I/O PLLs—located in each bank of the 48 I/Os

Fractional Synthesis PLLs

You can use the fractional synthesis PLLs to:

- Reduce the number of oscillators that are required on your board
- Reduce the number of clock pins that are used in the device by synthesizing multiple clock frequencies from a single reference clock source

⁽¹⁰⁾ Supported through software emulation and consumes additional MLAB blocks.



The fractional synthesis PLLs support the following features:

- Reference clock frequency synthesis for transceiver CMU and Advanced Transmit (ATX) PLLs
- Clock network delay compensation
- Zero-delay buffering
- Direct transmit clocking for transceivers
- Independently configurable into two modes:
 - Conventional integer mode equivalent to the general purpose PLL
 - Enhanced fractional mode with third order delta-sigma modulation
- PLL cascading

I/O PLLs

The integer mode I/O PLLs are located in each bank of 48 I/Os. You can use the I/O PLLs to simplify the design of external memory and high-speed LVDS interfaces.

In each I/O bank, the I/O PLLs are adjacent to the hard memory controllers and LVDS SERDES. Because these PLLs are tightly coupled with the I/Os that need to use them, it makes it easier to close timing.

You can use the I/O PLLs for general purpose applications in the core such as clock network delay compensation and zero-delay buffering.

Intel Arria 10 devices support PLL-to-PLL cascading.

FPGA General Purpose I/O

Intel Arria 10 devices offer highly configurable GPIOs. Each I/O bank contains 48 general purpose I/Os and a high-efficiency hard memory controller.

The following list describes the features of the GPIOs:

- Consist of 3 V I/Os for high-voltage application and LVDS I/Os for differential signaling
 - $-\,$ Up to two 3 V I/O banks, available in some devices, that support up to 3 V I/O standards
 - LVDS I/O banks that support up to 1.8 V I/O standards
- Support a wide range of single-ended and differential I/O interfaces
- LVDS speeds up to 1.6 Gbps
- Each LVDS pair of pins has differential input and output buffers, allowing you to configure the LVDS direction for each pair.
- Programmable bus hold and weak pull-up
- Programmable differential output voltage (V_{OD}) and programmable pre-emphasis



- Series (R_S) and parallel (R_T) on-chip termination (OCT) for all I/O banks with OCT calibration to limit the termination impedance variation
- On-chip dynamic termination that has the ability to swap between series and parallel termination, depending on whether there is read or write on a common bus for signal integrity
- Easy timing closure support using the hard read FIFO in the input register path, and delay-locked loop (DLL) delay chain with fine and coarse architecture

External Memory Interface

Intel Arria 10 devices offer massive external memory bandwidth, with up to seven 32bit DDR4 memory interfaces running at up to 2,400 Mbps. This bandwidth provides additional ease of design, lower power, and resource efficiencies of hardened highperformance memory controllers.

The memory interface within Intel Arria 10 FPGAs and SoCs delivers the highest performance and ease of use. You can configure up to a maximum width of 144 bits when using the hard or soft memory controllers. If required, you can bypass the hard memory controller and use a soft controller implemented in the user logic.

Each I/O contains a hardened DDR read/write path (PHY) capable of performing key memory interface functionality such as read/write leveling, FIFO buffering to lower latency and improve margin, timing calibration, and on-chip termination.

The timing calibration is aided by the inclusion of hard microcontrollers based on Intel's Nios[®] II technology, specifically tailored to control the calibration of multiple memory interfaces. This calibration allows the Intel Arria 10 device to compensate for any changes in process, voltage, or temperature either within the Intel Arria 10 device itself, or within the external memory device. The advanced calibration algorithms ensure maximum bandwidth and robust timing margin across all operating conditions.

In addition to parallel memory interfaces, Intel Arria 10 devices support serial memory technologies such as the Hybrid Memory Cube (HMC). The HMC is supported by the Intel Arria 10 high-speed serial transceivers which connect up to four HMC links, with each link running at data rates up to 15 Gbps.

Related Information

External Memory Interface Spec Estimator

Provides a parametric tool that allows you to find and compare the performance of the supported external memory interfaces in IntelFPGAs.

Memory Standards Supported by Intel Arria 10 Devices

The I/Os are designed to provide high performance support for existing and emerging external memory standards.



Table 20. Memory Standards Supported by the Hard Memory Controller

This table lists the overall capability of the hard memory controller. For specific details, refer to the External Memory Interface Spec Estimator and Intel Arria 10 Device Datasheet.

Memory Standard	Rate Support	Ping Pong PHY Support	Maximum Frequency (MHz)
DDR4 SDRAM	Quarter rate	Yes	1,067
		_	1,200
DDR3 SDRAM	Half rate	Yes	533
		_	667
	Quarter rate	Yes	1,067
		_	1,067
DDR3L SDRAM	Half rate	Yes	533
		_	667
	Quarter rate	Yes	933
		_	933
LPDDR3 SDRAM	Half rate	-	533
	Quarter rate	_	800

Table 21. Memory Standards Supported by the Soft Memory Controller

Memory Standard	Rate Support	Maximum Frequency (MHz)
RLDRAM 3 (11)	Quarter rate	1,200
QDR IV SRAM ⁽¹¹⁾	Quarter rate	1,067
QDR II SRAM	Full rate	333
	Half rate	633
QDR II+ SRAM	Full rate	333
	Half rate	633
QDR II+ Xtreme SRAM	Full rate	333
	Half rate	633

Table 22. Memory Standards Supported by the HPS Hard Memory Controller

The hard processor system (HPS) is available in Intel Arria 10 SoC devices only.

Memory Standard	Rate Support	Maximum Frequency (MHz)
DDR4 SDRAM	Half rate	1,200
DDR3 SDRAM	Half rate	1,067
DDR3L SDRAM	Half rate	933

⁽¹¹⁾ Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.